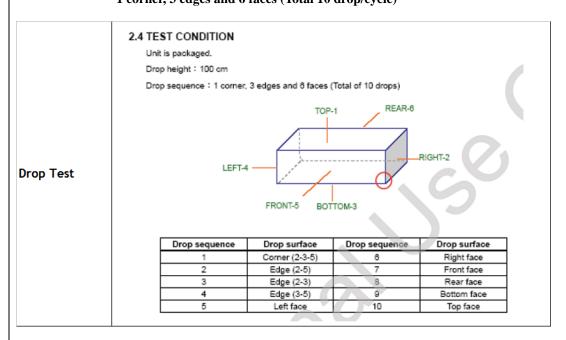
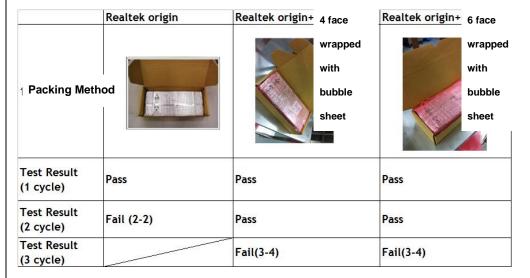
Product Change Notification

Preliminary L. Final E.					
PCN#	PC001-20121200209				
Supplier	Realtek Semiconductor Corp.				
Name					
Supplier	Antony Chien				
Contacts					
Change Category	☐ Chip related changes ☐ Process ☐ Design ☐ Specification ☐ Package Type ☐ Package material ☐ Testing software				
	Application related changes Schematics Layout BOM Software				
	 ■ Others □ EMS □ others ■ others Realtek Packing Method Optimum 				
Title of	Realtek Packing Method Optimum				
Change					
Change Description	1. Drop test condition: (refer to IEC & JIS)				
	Realtek origin Realtek origin+ Realtek origin+				
	Packing Method Packing Sheet Wrapped With bubble sheet Sheet Wrapped With bubble sheet				
	Ref Spec Ref Spec IEC(International Electrotechnical Commission)60068-2-32 & JIS(Japanese Industrial Standard)0202 Drop Height:100cm Drop sequence: 1 corner, 3 edges and 6 face (Total of 10 drop)				
	Drop test Index AL bag cannot be broken and IC not be damaged				

2. Drop test flow: Height :100cm 1 corner, 3 edges and 6 faces (Total 10 drop/cycle)



3. Drop Test Result:



- 1.Drop test: 6 face wrapped with bubble sheets =4 sites wrapped with bubble sheet >Realtek origin
- 2.To add the bubble sheet to enhance the protection-ability of dropping on edge than Realtek origin packing method.

4. Conclusion:

- To add the 4 face wrapped with bubble sheet solution for enhancing the protection-ability of dropping impact.
- The new packing method will be implemented from 2013 DC01 by running change.

	Appendix: Dimension of I	bubble sheet: L 460 mm W:35	50mm			
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		**************************************	L 460 mm	3		
	545	*******	L 400 IIIII			
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	78		_			
	1					
	W	:350mm				
	1	'				
	:					
Reason for	Packing Optimum					
Change						
Change	Major : □Class 1 (Approval necessary) Minor : ■Class 2					
Classification						
Product	None					
Affected						
Change	☐Product Mark ☐Ba	ack Mark Date Code	Others N/A			
Identification						
Key Date	Implementation	Samples Available	Last Date to Purchase Unch	anged Part		
	2013 DC01	.N/A	N/A			
Sites Affected	N/A					
Risk	Risk Level : High Medium Low					
Assessment						
Qualification	See Attachment(MSDS-LDPE-En.pdf & 氣泡布 CE_2012_23520E.pdf) □NA					
	Description as below:					
Customer	Company:					
Approval	Signature :		Date :			